



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



SERIES: HSS-B20-0635 | **DESCRIPTION:** HEAT SINK

FEATURES

- TO-220 package
- solder pin for secure PCB mounting
- round hole for component attachment
- black anodized finish



MODEL

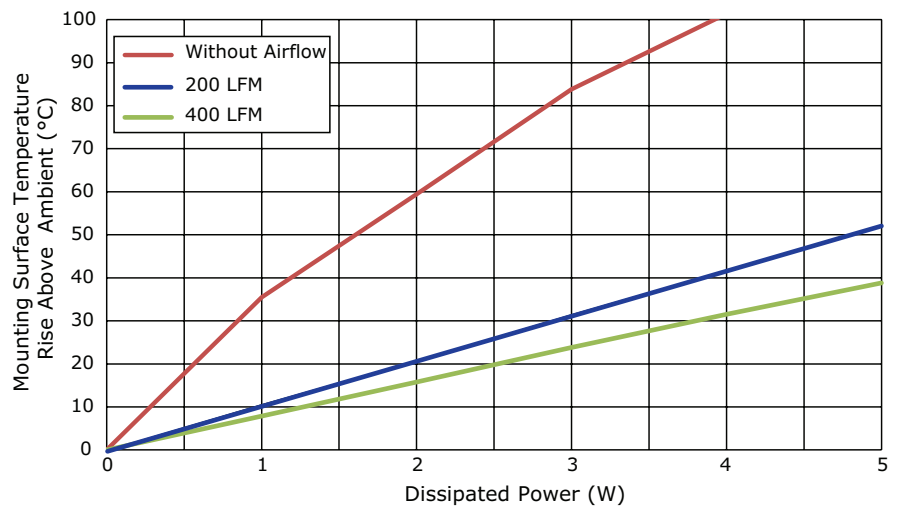
	fin height (mm)	thermal resistance ¹			power dissipation ¹ @ 75°C ΔT, nat conv (W)	
		@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)		@ 1 W, 400 LFM (°C/W)
HSS-B20-0635H	6.35	28.85	35.46	10.68	7.88	2.60
HSS-B20-0635H-01	9.53	27.78	33.93	9.51	6.84	2.70
HSS-B20-0635H-02	12.70	29.09	33.89	10.49	6.81	2.58

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

HSS-B20-0635H

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	35.46	10.68	7.88
2	59.42	20.81	15.77
3	83.82	31.59	23.83
4	101.40	41.80	31.52
5	122.52	52.02	38.83



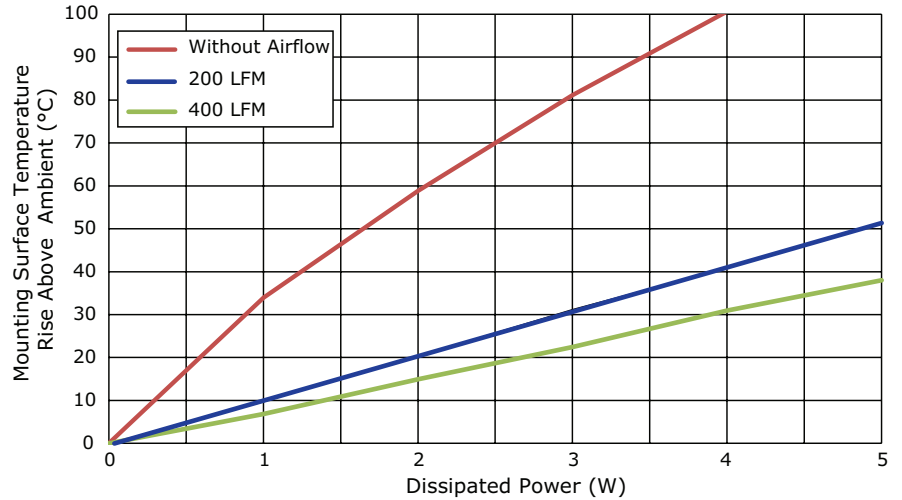
T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature

PERFORMANCE CURVES (CONTINUED)

HSS-B20-0635H-01

Power (W)	Heatsink Temperature Rise Above Ambient ($\Delta T = T_{hs} - T_a$) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	33.93	9.51	6.84
2	58.86	20.45	14.91
3	81.12	31.36	22.45
4	100.66	40.98	30.96
5	121.15	51.38	38.04

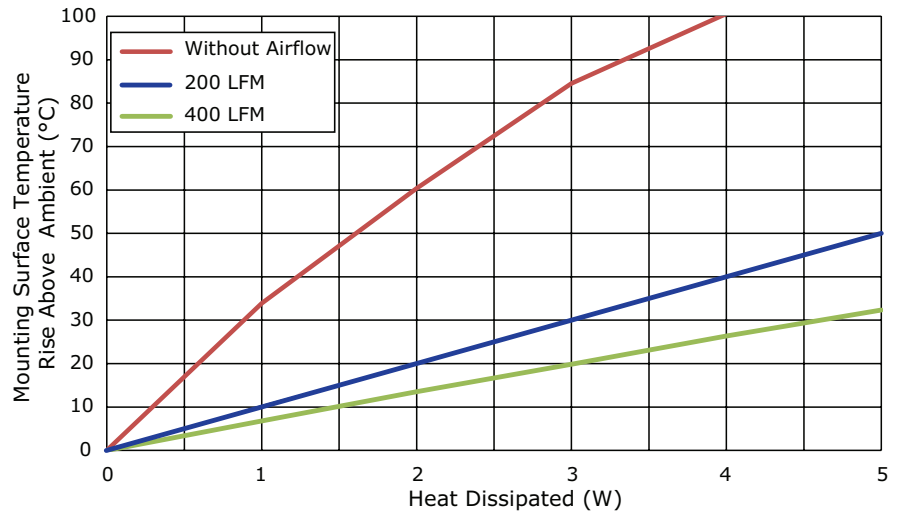
T_{hs} : "hot spot" temperature measured on the heatsink
 T_a : ambient temperature



HSS-B20-0635H-02

Power (W)	Heatsink Temperature Rise Above Ambient ($\Delta T = T_{hs} - T_a$) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	33.89	10.49	6.81
2	60.40	20.20	13.50
3	84.56	30.26	19.87
4	100.59	40.17	26.37
5	112.14	49.67	32.37

T_{hs} : "hot spot" temperature measured on the heatsink
 T_a : ambient temperature

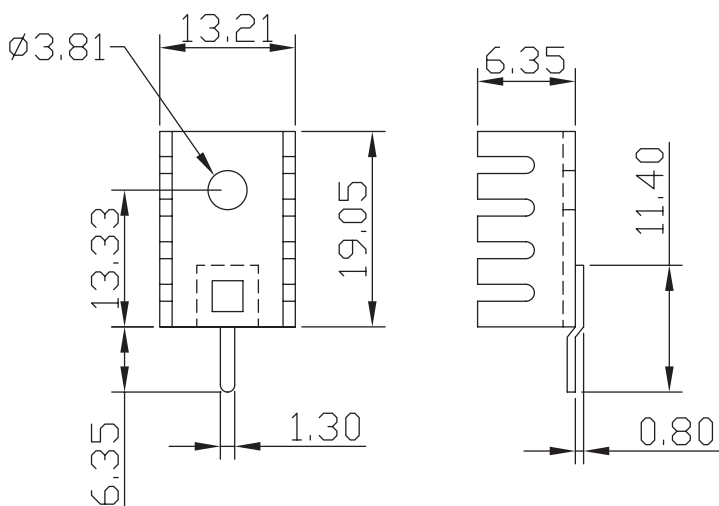


MECHANICAL DRAWING

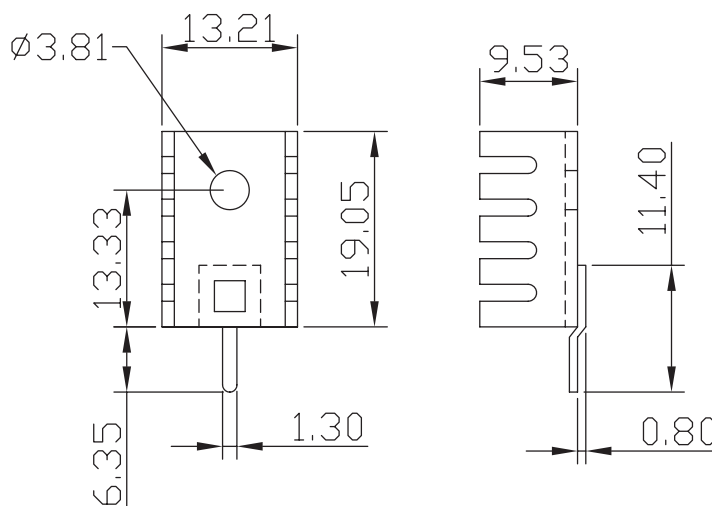
units: mm
tolerance: ±0.5 mm

MATERIAL	AL1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	HSS-B20-0635H: 1.5 g HSS-B20-0635H-01: 1.7 g HSS-B20-0635H-02: 2.0 g

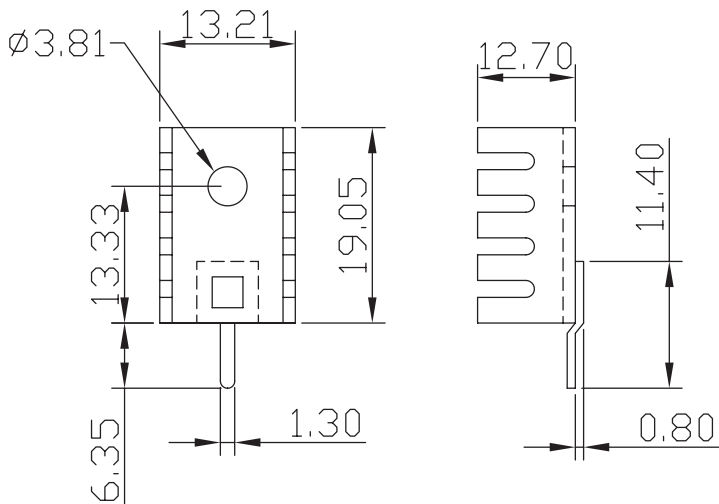
HSS-B20-0635H



HSS-B20-0635H-01



HSS-B20-0635H-02



REVISION HISTORY

rev.	description	date
1.0	initial release	03/29/2017

The revision history provided is for informational purposes only and is believed to be accurate.



CUI INC[®]

Headquarters
20050 SW 112th Ave.
Tualatin, OR 97062
800.275.4899

Fax 503.612.2383
cui.com
techsupport@cui.com

CUI offers a one (1) year limited warranty. Complete warranty information is listed on our website.

CUI reserves the right to make changes to the product at any time without notice. Information provided by CUI is believed to be accurate and reliable. However, no responsibility is assumed by CUI for its use, nor for any infringements of patents or other rights of third parties which may result from its use.

CUI products are not authorized or warranted for use as critical components in equipment that requires an extremely high level of reliability. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.